

CLAIMS

1. (amended) A composition for removing etch and/or ash residue or contaminants from a semiconductor substrate comprising;

- (A) from 80 to 90 wt% of a water soluble organic solvent,
(B) from 3 to 10 wt% of a sulfonic acid or its corresponding salt, and
(C) from 5 to 50 wt% water.

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2. (original) The composition as claimed in claim 1, further comprising a corrosion inhibitor.

3. (original) The composition as claimed in claim 1, wherein the water soluble organic solvent is monoethanolamine, N-methylethanolamine, dimethylsulfoxide, dimethylacetamide or mixtures thereof.

4. (original) The composition as claimed in claim 1, wherein the sulfonic acid or its corresponding salt is p-toluene sulfonic acid, 1,5-naphthalene disulfonic acid, 4-ethylbenzene sulfonic acid, dodecylbenzene sulfonic acid or mixtures thereof.

5. (original) The composition as claimed in claim 2, wherein the corrosion inhibitor is gallic acid, catechol, benzotriazole, benzoic acid, malonic acid, ammonium malonate or mixtures thereof.

6. (amended) A composition, for removing etch and/or ash residue or contaminants from a semiconductor substrate comprising:

- (A) from 30 to 85 wt% of a water soluble organic solvent,
(B) from 1 to 20 wt% of a sulfonic acid or its corresponding salt,
(C) from 5 to 50 wt% water.

7. (original) The composition as claimed in claim 6, further comprising; from 0.1 to 15 wt% of a corrosion inhibitor.

8. (cancelled) A method of removing photoresist, etch and/or ash residue, or contaminants from a semiconductor substrate, comprising; contacting the semiconductor substrate with a composition, comprising:

(A) a water soluble organic solvent,

(B) a sulfonic acid or its corresponding salt, and

(C) water;

for a period of time sufficient to remove the photoresist, etch and/or ash residue or contaminants.

9. (cancelled) The method as claimed in claim 8, wherein the composition further comprises a corrosion inhibitor.

10. (cancelled) The method as claimed in claim 8, wherein the water soluble organic solvent is monoethanolamine, N-methylethanolamine, dimethylsulfoxide, dimethylacetamide or mixtures thereof.

11. (cancelled) The method as claimed in claim 8, wherein the sulfonic acid or its corresponding salt is p-toluene sulfonic acid, 1,5-naphthalene disulfonic acid, 4-ethylbenzene sulfonic acid, dodecylbenzene sulfonic acid or mixtures thereof,

12. (cancelled) The method as claimed in claim 9, wherein the corrosion inhibitor is gallic acid, catechol, benzotriazole, benzoic acid, malonic acid, ammonium malonate or mixtures thereof.